



Session Title:	[TD3] HARC Etching/Green Etch Technology
Session Date:	November 21 (Tue.), 2023
Session Time:	14:25-16:15
Session Room:	Room D (Grand Ballroom 3, 2F)
Session Chair:	Prof. Shin Jae You (Chungnam Nat'l Univ., Korea)

[TD3-1] 14:25-14:45

Study of Redeposition Effects on the High Aspect Ratio SiO₂ Etching Profile Evolution

Wonnyoung Jeong, Byeongyeop Choi, Youngseok Lee, Sijun Kim, Chulhee Cho, Inho Seong, Minsu Choi, and Shinjae You (Chungnam Nat'l Univ., Korea)

[TD3-2] 14:45-15:05

A Study on the High-Aspect-Ratio Oxide Etching Characteristics Using a Hexafluoroisobutylene

Gilyoung Choi, Jinhyuk Kim, and Kwang-Ho Kwon (Korea Univ., Korea)

[TD3-3] 15:05-15:25

Innovative Cyclic Etching Process for High-Aspect-Ratio SiO₂ Features Using Low-GWP Heptafluoropropyl Methyl Ether

Sanghyun You and Chang-Koo Kim (Ajou Univ., Korea)

[TD3-4] [Invited] 15-25-15:55

Green Technologies in Advanced Etching Process

Huichan Seo (SK hynix, Korea)

[TD3-5] 15-55-16:15

The Investigation of Etching Characteristics between Isomer Gases of Low GWP Etch Gases

Jeonga Ju, Jinkoo Park (UNIST, Korea), Yeongjin Lim, Bongsuk Kim (Foosung, Korea), and Hongsik Jeong (UNIST, Korea)